

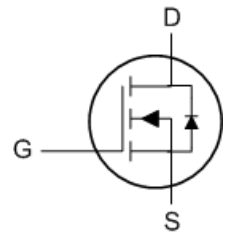
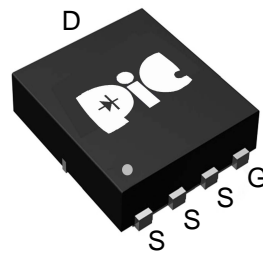
### ➤ General Description

This PAN40TY06Y N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent  $R_{ds(On)}$  performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### ➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

### ➤ DFN5X6A-EP1



### ➤ Application

- DC/DC Primary Side Switch
- Industrial Synchronous
- Rectification Load Switch
- DC/DC Converters

### ➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_C=25^\circ C$	60	A
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_C=100^\circ C$	45	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	120	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	76	mJ
Avalanche Current	$I_{AS}$	39	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_C=25^\circ C$	46	W
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to 150	$^\circ C$
Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	2.7	$^\circ C/W$

### ➤ Electrical Characteristics ( $T_J=25^\circ C$ Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BVDSS	$V_{GS}=0V, I_D=250\mu A$	40	---	---	V
BVDSS Temperature Coefficient	$\Delta BVDSS/\Delta T$	Reference to $25^\circ C, I_D=1mA$	---	0.034	---	$V/^\circ C$
Static Drain-Source On-Resistance <sup>2</sup>	RDS(ON)	$V_{GS}=10V, I_D=12A$	---	---	7.5	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	---	10	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.5	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-4.96	---	$mV/^\circ C$
Drain-Source Leakage Current	IDSS	$V_{DS}=32V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
Gate-Source Leakage Current	IGSS	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
Forward Transconductance	gfs	$V_{DS}=5V, I_D=12A$	---	39	---	S
Gate Resistance	Rg	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.6	---	$\Omega$
Total Gate Charge (4.5V)	Qg	$V_{DS}=20V, V_{GS}=4.5V, I_D=12A$	---	18.8	---	nC
Gate-Source Charge	Qgs		---	4.7	---	
Gate-Drain Charge	Qgd		---	8.2	---	
Turn-On Delay Time	Td(on)	$V_{DD}=15V, V_{GS}=10V, RG=3.3, I_D=1A$	---	14.3	---	ns
Rise Time	Tr		---	2.6	---	
Turn-Off Delay Time	Td(off)		---	77	---	
Fall Time	Tf		---	4.8	---	
Input Capacitance	Ciss	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	2332	---	pF
Output Capacitance	Coss		---	193	---	
Reverse Transfer Capacitance	Crss		---	138	---	

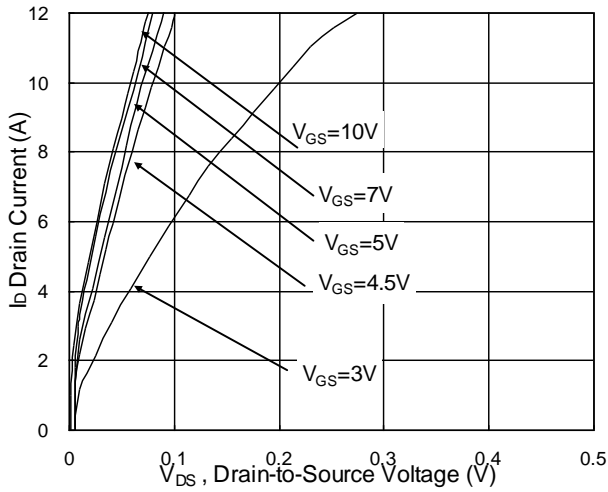
### ➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,5</sup>	IS	$V_G=V_D=0V, \text{Force Current}$	---	---	60	A
Pulsed Source Current <sup>2,5</sup>	ISM		---	---	120	A
Diode Forward Voltage <sup>2</sup>	VSD	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1	V

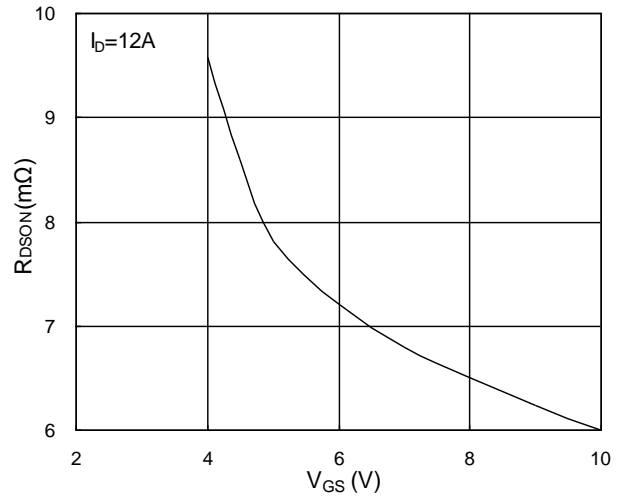
Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=39A$
- 4.Ensure that the channel temperature does not exceed  $150^\circ C$ .
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

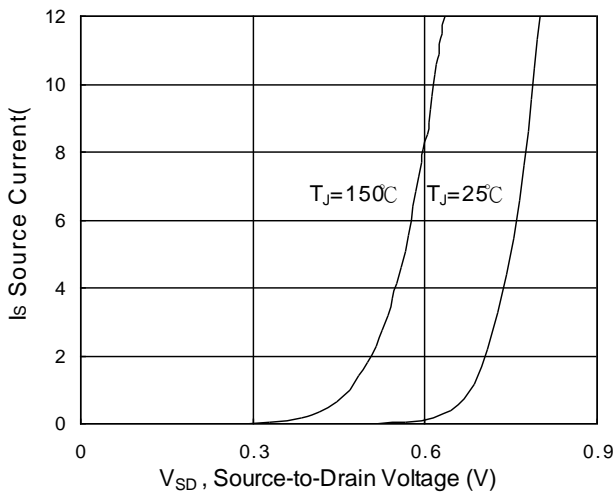
### ➤ Typical Characteristics



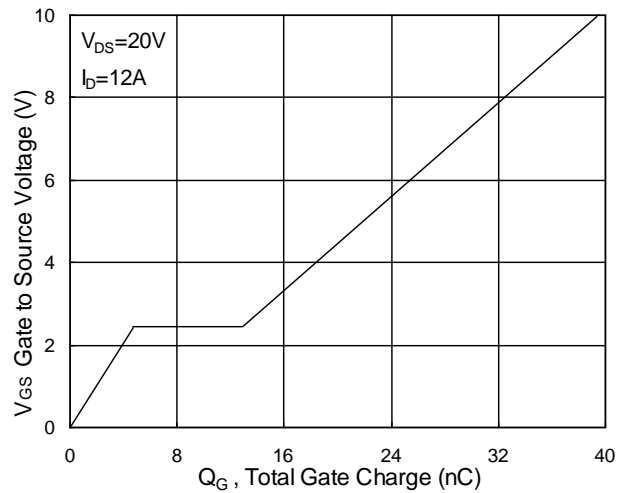
**Fig.1 Typical Output Characteristics**



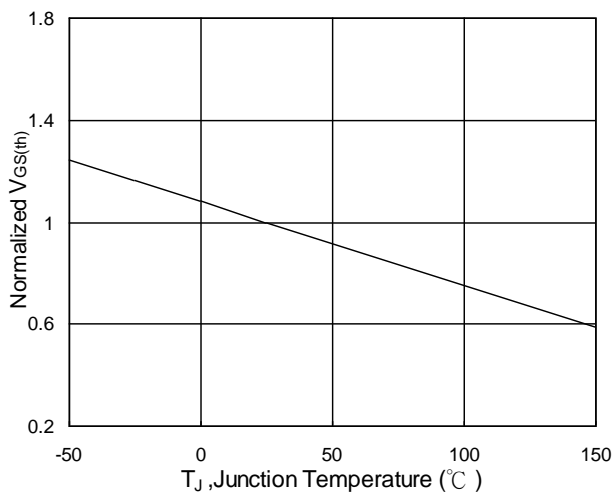
**Fig.2 On-Resistance vs. G-S Voltage**



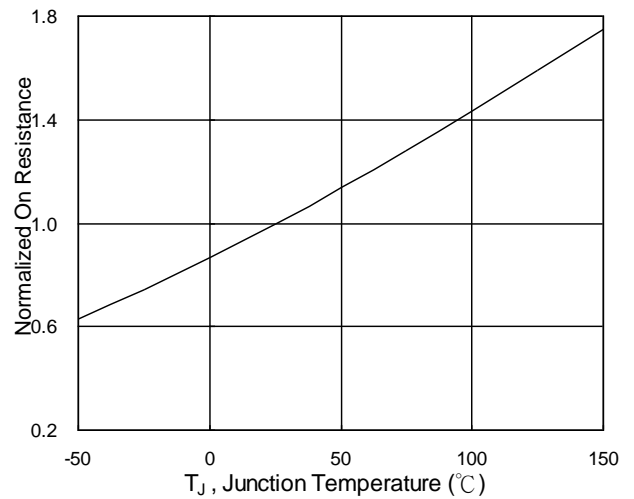
**Fig.3 Forward Characteristics of Reverse**



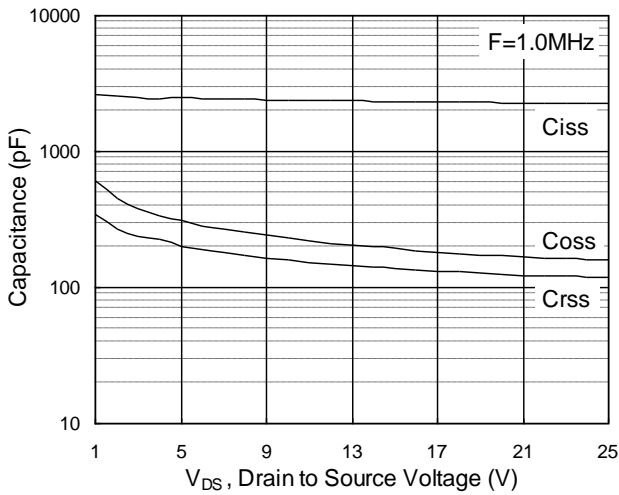
**Fig.4 Gate-Charge Characteristics**



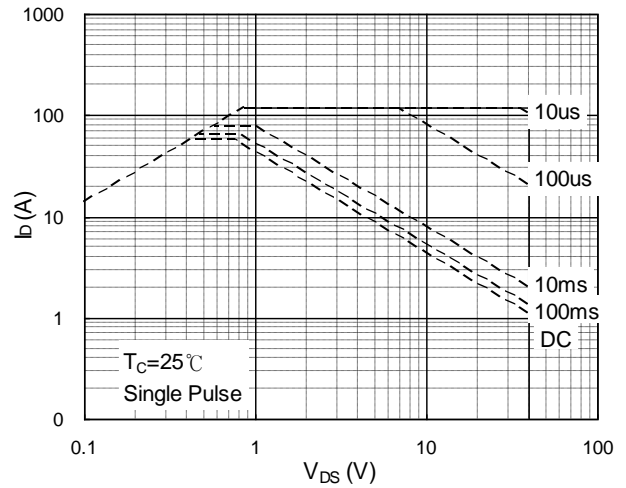
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



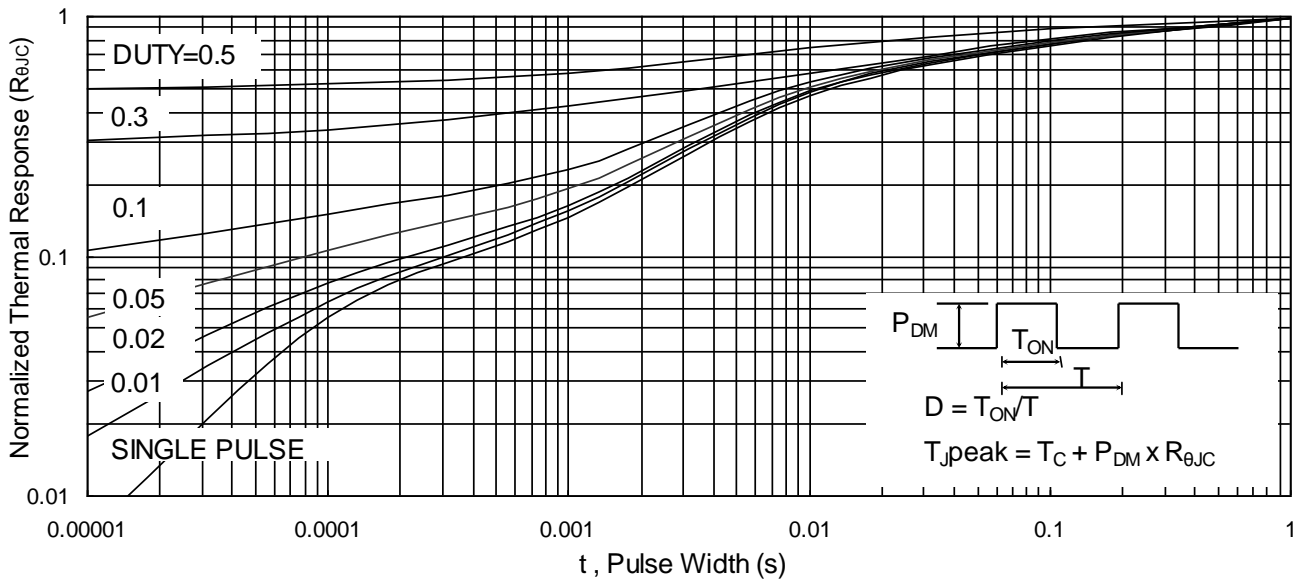
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



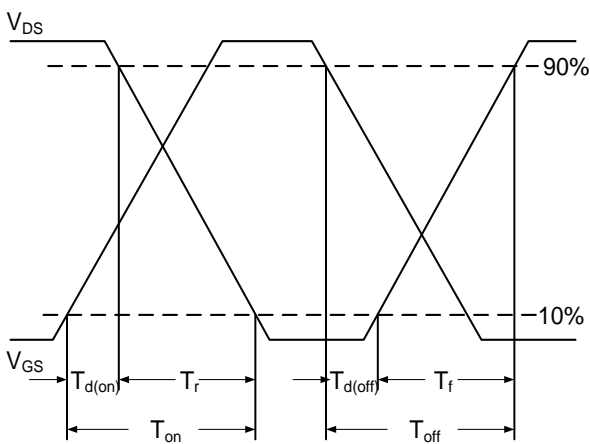
**Fig.7 Capacitance**



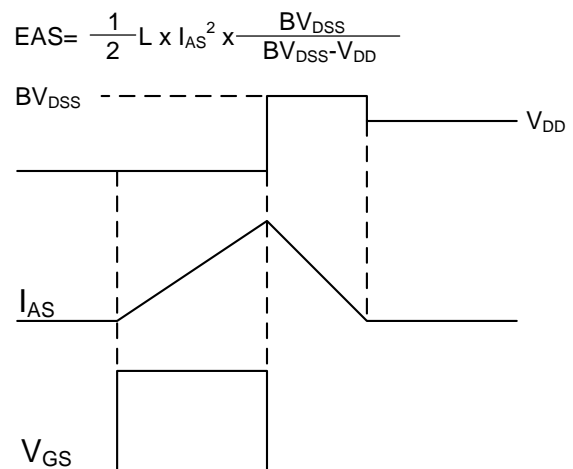
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

## ➤ Recommend IR Reflow Soldering Thermal Profile

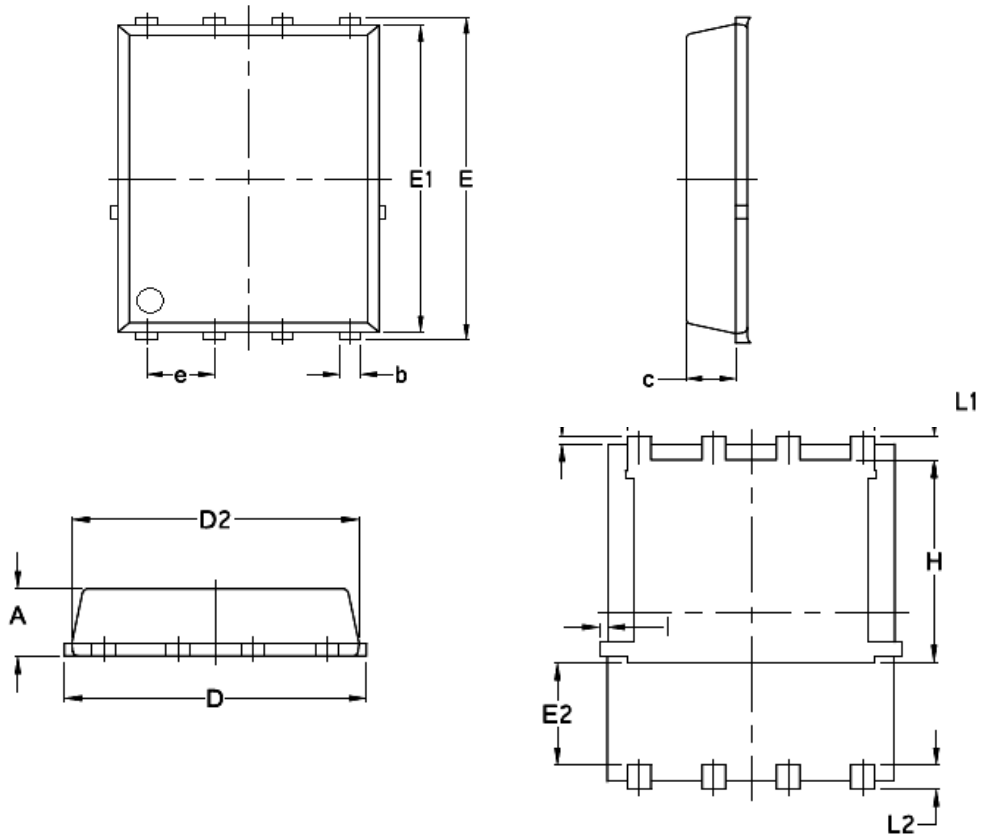


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

## ➤ Ordering Information

Part Number	Description	Quantity
PAN40TY06Y	DFN5X6A-EP1 Reel	3000 pcs

### ➤ Package Information ( DFN5X6A-EP1 )



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
I	---	0.18	---	0.0070
E	5.90	6.15	0.2323	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.10	---	0.0433	---
e	1.27 BSC		0.05 BSC	
H	3.30	3.78	0.1299	0.1488
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.61	0.0150	0.0240
L2	0.38	0.71	0.0150	0.0279

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